Chipsmall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

TCA0372, TCA0372B

1.0 A Output Current, Dual Power Operational Amplifiers

The TCA0372 is a monolithic circuit intended for use as a power operational amplifier in a wide range of applications, including servo amplifiers and power supplies. No deadband crossover distortion provides better performance for driving coils.

Features

- Output Current to 1.0 A
- Slew Rate of 1.3 V/μs
- Wide Bandwidth of 1.1 MHz
- Internal Thermal Shutdown
- Single or Split Supply Operation
- Excellent Gain and Phase Margins
- Common Mode Input Includes Ground
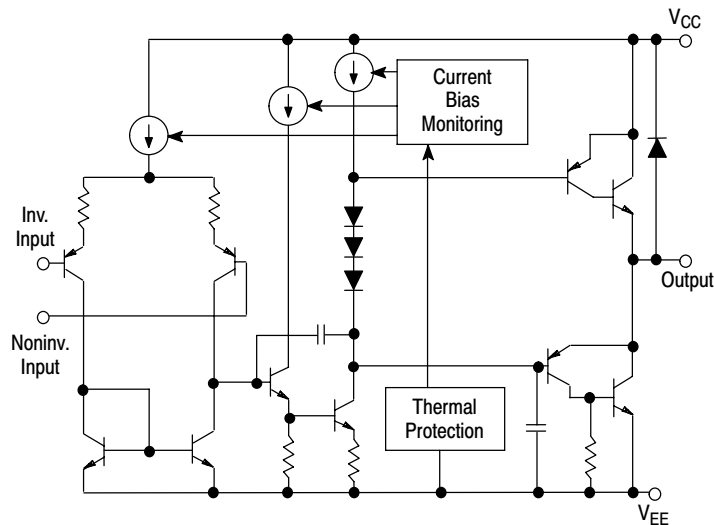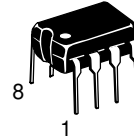- Zero Deadband Crossover Distortion
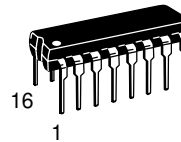- Pb−Free Packages are Available*
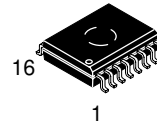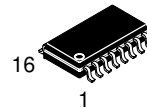
ON Semiconductor®

http://onsemi.com

PDIP−8
DP1 SUFFIX
CASE 626

PDIP−16
DP2 SUFFIX
CASE 648

SOIC−16W
DW SUFFIX
CASE 751G

SOEIAJ−16
DM2 SUFFIX
CASE 966

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 6 of this data sheet.

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

Figure 1. Representative Block Diagram

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Supply Voltage (from V_{CC} to V_{EE})	V_S	40	V
Input Differential Voltage Range	V_{IDR}	Note 1	V
Input Voltage Range	V_{IR}	Note 1	V
Junction Temperature (Note 2)	T_J	+150	°C
Operating Temperature Range	T_A	−40 to +125	°C
Storage Temperature Range	T_{stg}	−55 to +150	°C
DC Output Current	I_O	1.0	A
Peak Output Current (Nonrepetitive)	$I_{(max)}$	1.5	A
Thermal Resistance, Junction−to−Air Case 626 Case 648 Case 751G	$R_{\theta JA}$	 137 72 80	°C/W
Thermal Resistance, Junction−to−Case Case 626 Case 648 Case 751G	$R_{\theta JC}$	 23 10 12	°C/W

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.
1. Either or both input voltages should not exceed the magnitude of V_{CC} or V_{EE}.
2. Power dissipation must be considered to ensure maximum junction temperature (T_J) is not exceeded.

DC ELECTRICAL CHARACTERISTICS (V_{CC} = +15 V, V_{EE} = −15 V, R_L connected to ground, T_A = −40° to +125°C.)

Characteristics	Symbol	Min	Typ	Max	Unit
Input Offset Voltage (V_{CM} = 0) T_A = +25°C T_A, T_{low} to T_{high}	V_{IO}	 – –	 1.0 –	 15 20	mV
Average Temperature Coefficient of Offset Voltage	$\Delta V_{IO}/\Delta T$	–	20	–	μV/°C
Input Bias Current (V_{CM} = 0)	I_{IB}	–	100	500	nA
Input Offset Current (V_{CM} = 0)	I_{IO}	–	10	50	nA
Large Signal Voltage Gain V_O = ±10 V, R_L = 2.0 k	A_{VOL}	30	100	–	V/mV
Output Voltage Swing (I_L = 100 mA) T_A = +25°C T_A = T_{low} to T_{high} T_A = +25°C T_A = T_{low} to T_{high}	V_{OH} V_{OL}	 14.0 13.9 – –	 14.2 – −14.2 –	 – – −14.0 −13.9	V
Output Voltage Swing (I_L = 1.0 A) V_{CC} = +24 V, V_{EE} = 0 V, T_A = +25°C V_{CC} = +24 V, V_{EE} = 0 V, T_A = T_{low} to T_{high} V_{CC} = +24 V, V_{EE} = 0 V, T_A = +25°C V_{CC} = +24 V, V_{EE} = 0 V, T_A = T_{low} to T_{high}	V_{OH} V_{OL}	 22.5 22.5 – –	 22.7 – 1.3 –	 – – 1.5 1.5	V
Input Common Mode Voltage Range T_A = +25°C T_A = T_{low} to T_{high}	V_{ICR}	V_{EE} to (V_{CC} −1.0) V_{EE} to (V_{CC} −1.3)			V
Common Mode Rejection Ratio (R_S = 10 k)	CMRR	70	90	–	dB
Power Supply Rejection Ratio (R_S = 100 Ω)	PSRR	70	90	–	dB

Power Supply Current
T_A = +25°C   TCA0372
                TCA0372B
T_A = T_{low} to T_{high} TCA0372
                TCA0372B
	I_D	
		–
		–
		–
		–
			
			5.0
			8.0
			–
			–
				
				10
				10
				14
				14
					mA

AC ELECTRICAL CHARACTERISTICS (V_{CC} = +15 V, V_{EE} = −15 V, R_L connected to ground, T_A = +25°C, unless otherwise noted.)

Characteristics	Symbol	Min	Typ	Max	Unit
Slew Rate (V_{in} = −10 V to +10 V, R_L = 2.0 k, C_L = 100 pF) A_V = −1.0, T_A = T_{low} to T_{high}	SR	1.0	1.4	–	V/μs
Gain Bandwidth Product (f = 100 kHz, C_L = 100 pF, R_L = 2.0 k) T_A = 25°C T_A = T_{low} to T_{high}	GBW	 0.9 0.7	 1.4 –	 – –	MHz
Phase Margin T_J = T_{low} to T_{high} R_L = 2.0 k, C_L = 100 pF	ϕ_m	–	65	–	Degrees
Gain Margin R_L = 2.0 k, C_L = 100 pF	A_m	–	15	–	dB
Equivalent Input Noise Voltage R_S = 100 Ω, f = 1.0 to 100 kHz	e_n	–	22	–	$nV/\sqrt{Hz}$
Total Harmonic Distortion A_V = −1.0, R_L = 50 Ω, V_O = 0.5 VRMS, f = 1.0 kHz	THD	–	0.02	–	%

NOTE: In case V_{EE} is disconnected before V_{CC}, a diode between V_{EE} and Ground is recommended to avoid damaging the device.
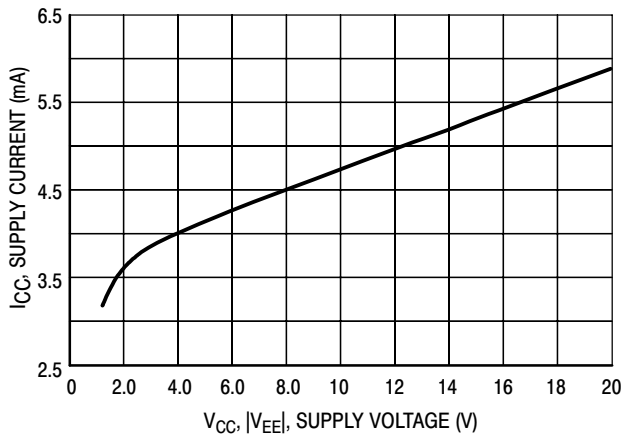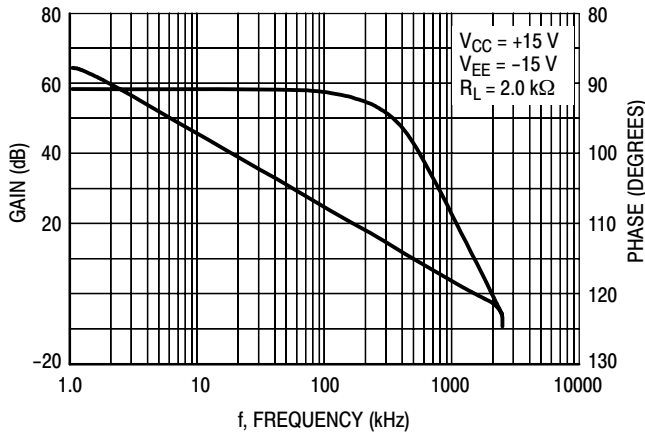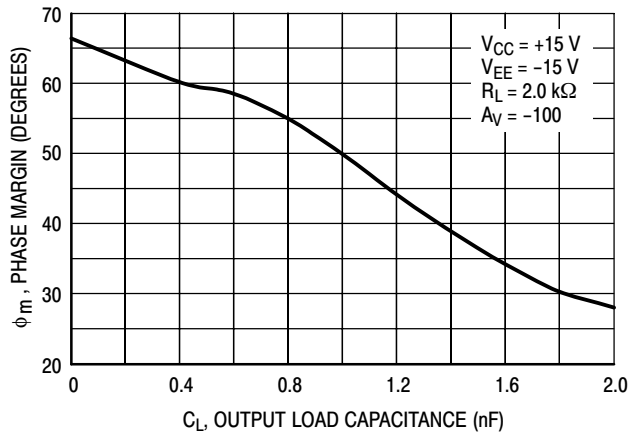
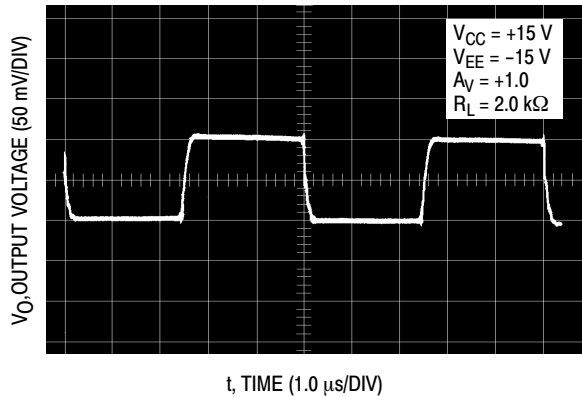**Figure 2. Supply Current versus Supply
Voltage with No Load**
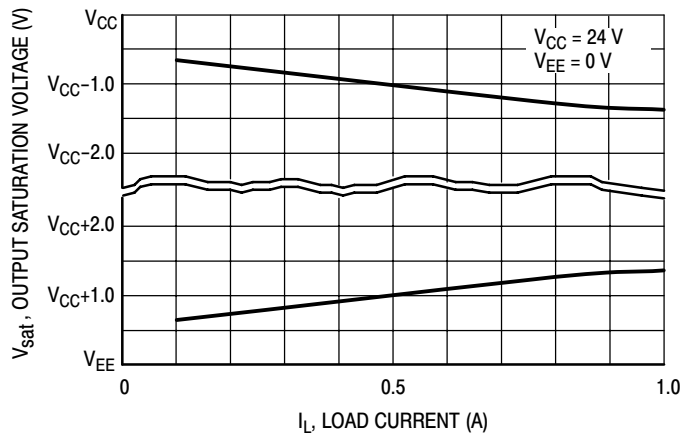
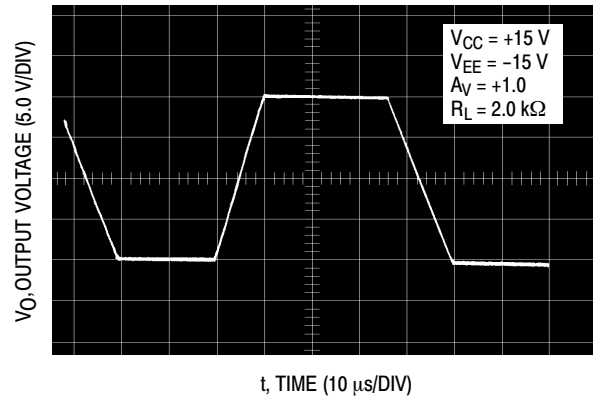**Figure 3. Output Saturation Voltage
versus Load Current**

**Figure 4. Voltage Gain and Phase
versus Frequency**

**Figure 5. Phase Margin versus Output
Load Capacitance**

Figure 6. Small Signal Transient Response

Figure 7. Large Signal Transient Response

V_CC = +15 V
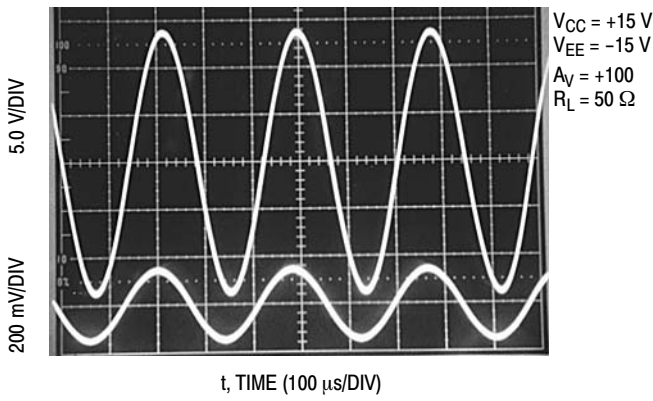V_EE = −15 V
A_V = +100
R_L = 50 Ω

$V_{CC} = +15\ V$
$V_{EE} = -15\ V$
$A_V = +100$
$R_L = 50\ \Omega$

5.0 V/DIV

200 mV/DIV

t, TIME (100 μs/DIV)

Figure 8. Sine Wave Response

V_S = Logic Supply Voltage
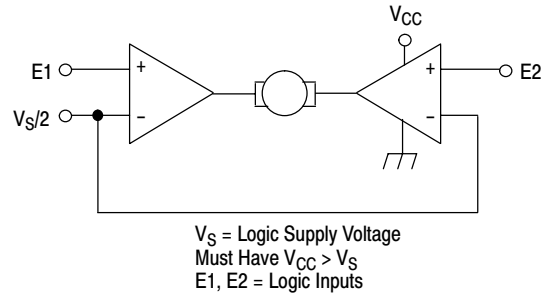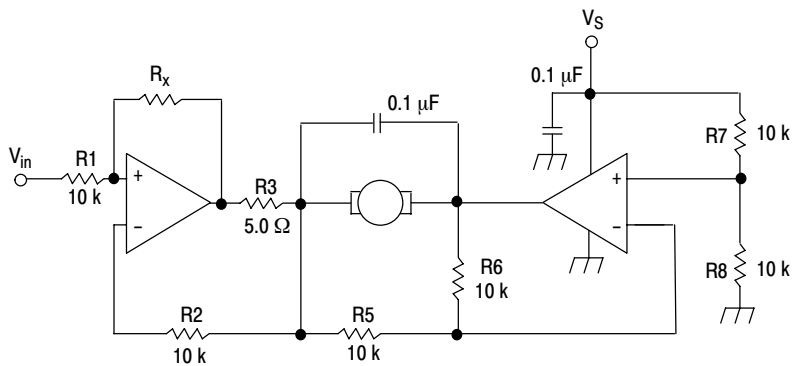Must Have $V_{CC} > V_S$
E1, E2 = Logic Inputs

Figure 9. Bidirectional DC Motor Control with Microprocessor−Compatible Inputs

For circuit stability, ensure that $R_x > \dfrac{2R3 \cdot R1}{R_M}$ where, R_M = internal resistance of motor.

The voltage available at the terminals of the motor is: $V_M = 2\left(V_1 - \dfrac{V_S}{2}\right) + |R_o| \cdot I_M$

where, $|R_o| = \dfrac{2R3 \cdot R1}{R_x}$ and I_M is the motor current.

Figure 10. Bidirectional Speed Control of DC Motors
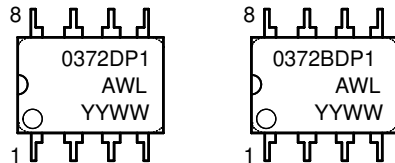
TCA0372, TCA0372B

ORDERING INFORMATION

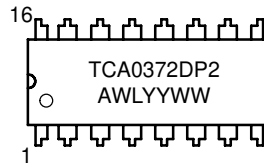| Device	Package	Shipping†
TCA0372DW	SOIC−16W	47 Units / Rail
TCA0372DWG	SOIC−16W (Pb−Free)	47 Units / Rail
TCA0372DWR2	SOIC−16W	1000 Tape & Reel
TCA0372DWR2G	SOIC−16W (Pb−Free)	1000 Tape & Reel
TCA0372BDWR2	SOIC−16W	1000 Tape & Reel
TCA0372BDWR2G	SOIC−16W (Pb−Free)	1000 Tape & Reel
TCA0372DP1	PDIP−8	50 Units / Rail
TCA0372DP1G	PDIP−8 (Pb−Free)	50 Units / Rail
TCA0372BDP1	PDIP−8	50 Units / Rail
TCA0372BDP1G	PDIP−8 (Pb−Free)	50 Units / Rail
TCA0372DP2	PDIP−16	25 Units / Rail
TCA0372DP2G	PDIP−16 (Pb−Free)	25 Units / Rail
TCA0372DM2EL	SOEIAJ−16	2500 Tape & Reel
TCA0372DM2ELG	SOEIAJ−16 (Pb−Free)	2500 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
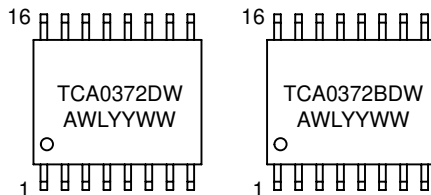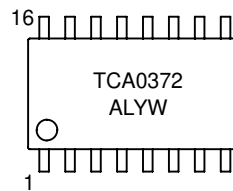
MARKING DIAGRAMS

PDIP−8
DP1 SUFFIX
CASE 626

8

0372DP1
AWL
YYWW

1

8

0372BDP1
AWL
YYWW

1

PDIP−16
DP2 SUFFIX
CASE 648

16

TCA0372DP2
AWLYYWW

1

SOIC−16W
DW SUFFIX
CASE 751G

16

TCA0372DW
AWLYYWW

1

16

TCA0372BDW
AWLYYWW

1

SOEIAJ−16
DM2 SUFFIX
CASE 966

16

TCA0372
ALYW

1

A	= Assembly Location
WL, L	= Wafer Lot
YY, Y	= Year
WW, W	= Work Week

TCA0372, TCA0372B

PIN CONNECTIONS

CASE 648

Output A	1	16	GND
V_{CC}	2	15	GND
Output B	3	14	GND
V_{EE}/GND	4	13	GND
Inputs B {	5	12	GND
	6	11	GND
Inputs A {	7	10	GND
	8	9	GND

(Top View)
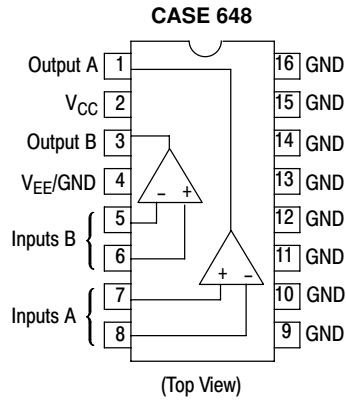
*Pins 4 and 9 to 16 are internally connected.

CASE 626

Output A	1	8	} Inputs A
V_{CC}	2	7	
Output B	3	6	} Inputs B
V_{EE}/GND	4	5	

(Top View)

CASE 751G

V_{CC}	1	16	Output A
Output B	2	15	NC
NC	3	14	NC
V_{EE}/GND {	4	13	} V_{EE}/GND
	5	12	
NC	6	11	NC
Inputs B {	7	10	} Inputs A
	8	9	

(Top View)

CASE 966

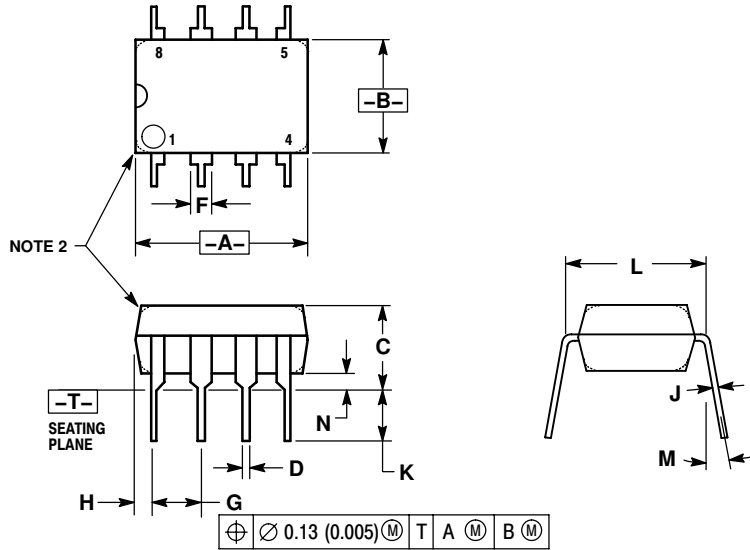|			
V_{EE}/GND	1	16	V_{EE}/GND
NC	2	15	NC
Output A	3	14	} Inputs A
V_{CC}	4	13	
Output B	5	12	} Inputs B
NC	6	11	
NC	7	10	NC
V_{EE}/GND	8	9	V_{EE}/GND

(Top View)

PACKAGE DIMENSIONS

PDIP−8
DP1 SUFFIX
CASE 626−05
ISSUE L

NOTES:
1. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
2. PACKAGE CONTOUR OPTIONAL (ROUND OR SQUARE CORNERS).
3. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.40	10.16	0.370	0.400
B	6.10	6.60	0.240	0.260
C	3.94	4.45	0.155	0.175
D	0.38	0.51	0.015	0.020
F	1.02	1.78	0.040	0.070
G	2.54 BSC		0.100 BSC	
H	0.76	1.27	0.030	0.050
J	0.20	0.30	0.008	0.012
K	2.92	3.43	0.115	0.135
L	7.62 BSC		0.300 BSC	
M	---	10°	---	10°
N	0.76	1.01	0.030	0.040

PDIP−16
DP2 SUFFIX
CASE 648−08
ISSUE T
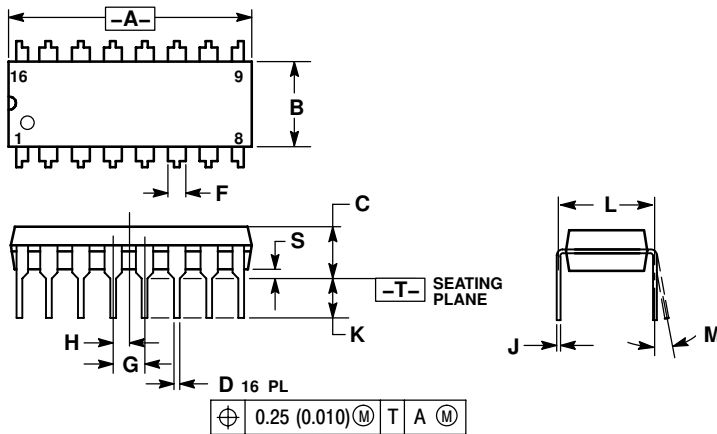
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

TCA0372, TCA0372B

PACKAGE DIMENSIONS

SOIC–16W
### DW SUFFIX
CASE 751G–03
ISSUE B
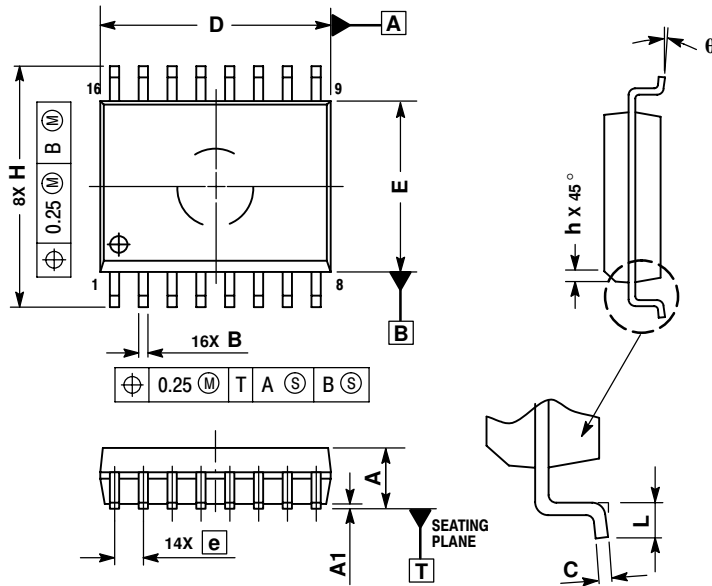
NOTES:
1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS D AND E DO NOT INLCUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF THE B DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS	
	MIN	MAX
A	2.35	2.65
A1	0.10	0.25
B	0.35	0.49
C	0.23	0.32
D	10.15	10.45
E	7.40	7.60
e	1.27 BSC	
H	10.05	10.55
h	0.25	0.75
L	0.50	0.90
θ	0 °	7 °

SOEIAJ–16
DM2 SUFFIX
CASE 966–01
ISSUE O

DETAIL P

VIEW P
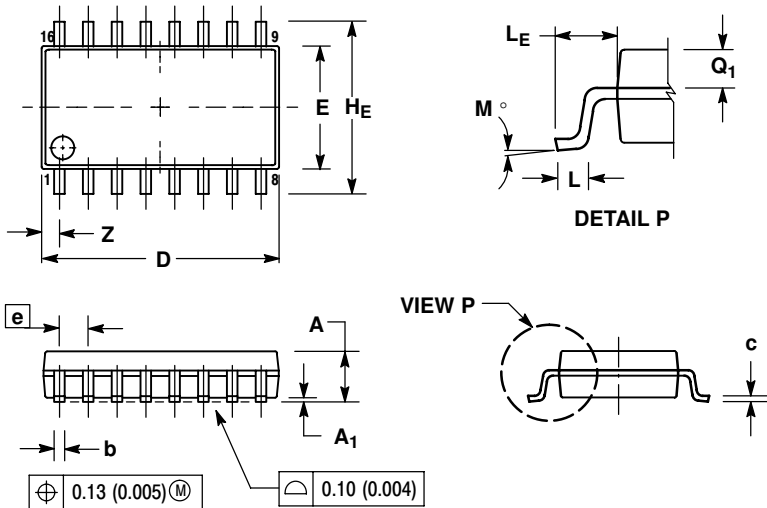
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
Q1	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031

TCA0372, TCA0372B